
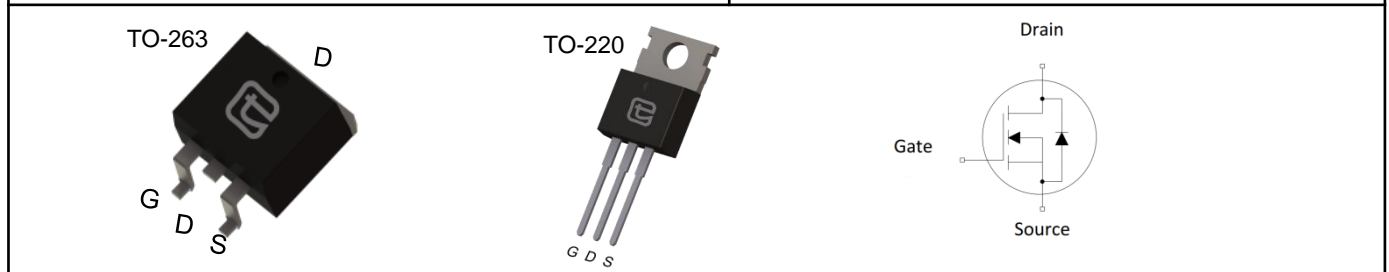


**100V N-Channel Trench MOSFET(Preliminary)**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>● Trench Power Technology</li> <li>● Low <math>R_{DS(ON)}</math></li> <li>● Low Gate Charge</li> <li>● Optimized for fast-switching Applications</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>● Synchronous Rectification in DC/DC and AC/DC Converters</li> <li>● Isolated DC/DC Converters in Telecom and Industrial</li> </ul>	<p><b>Product Summary</b></p> <p><math>V_{DS}</math> 100V</p> <p><math>I_D</math> (at <math>V_{GS}=10V</math>) 65A</p> <p><math>R_{DS(ON)}</math> (at <math>V_{GS}=10V</math>) &lt; 17m<math>\Omega</math></p> <p>100% UIS Tested</p> 
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Device	Package	Form	Marking
TTB65N10A	TO-252	Tape & Reel	65N10A
TTP65N10A	TO-220	Tube	65N10A

Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)			
Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>B</sup>	$I_D$	$T_C = 25^\circ\text{C}$	65
		$T_C = 100^\circ\text{C}$	45.5
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	195	A
Avalanche Current <sup>A</sup>	$I_{AS}$	21	A
Single Pulse Avalanche Energy	$E_{AS}$	66	mJ
Power Dissipation <sup>C</sup>	$P_D$	$T_C = 25^\circ\text{C}$	200
		$T_C = 100^\circ\text{C}$	100
Operating Junction and Storage Temperature Range	$T_J, T_{sgt}$	-55 to 175	$^\circ\text{C}$

Thermal Resistance			
Parameter	Symbol	Maximum	Units
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.75	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	100	



Electrical Characteristics( $T_J = 25^\circ\text{C}$ unless otherwise noted)							
Symbol	Parameter	Conditions	Value			Units	
			Min	Typ	Max		
<b>STATIC PARAMETERS</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	--	--	V	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	$T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
			$T_J = 100^\circ\text{C}$	--	--	25	
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	--	--	$\pm 100$	nA	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V	
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	--	14	19	m $\Omega$	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{V}, I_D = 20\text{A}$	24	--	--	S	
$V_{SD}$	Diode Forward Voltage	$I_S = 20\text{A}, V_{GS} = 0\text{V}$	--	--	1	V	
$I_S$	Maximum Body-Diode Continuous Current <sup>B</sup>		--	--	65	A	
<b>DYNAMIC PARAMETERS</b>							
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$	--	5523	--	$\text{pF}$	
$C_{oss}$	Output Capacitance		--	182	--		
$C_{rss}$	Reverse Transfer Capacitance		--	164	--		
<b>SWITCHING PARAMETERS</b>							
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}, I_D = 30\text{A}$	--	97	--	nC	
$Q_{gs}$	Gate Source Charge		--	26	--		
$Q_{gd}$	Gate Drain Charge		--	20	--		
$t_{D(on)}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DS} = 40\text{V}, I_D = 30\text{A}, R_G = 2.5\Omega$	--	25	--	ns	
$t_r$	Turn-On Rise Time		--	20	--		
$T_{D(off)}$	Turn-Off Delay Time		--	73	--		
$t_f$	Turn-Off Fall Time		--	35	--		
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = 30\text{A}, di/dt = 100\text{A}/\mu\text{s}$	--	38	--	ns	
$Q_{rr}$	Body Diode Reverse Recovery Charge		--	60	--	nC	

A. Single pulse width limited by maximum junction temperature.

B. The maximum current rating is package limited.

C. The power dissipation  $P_D$  is based on  $T_{J(MAX)} = 175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

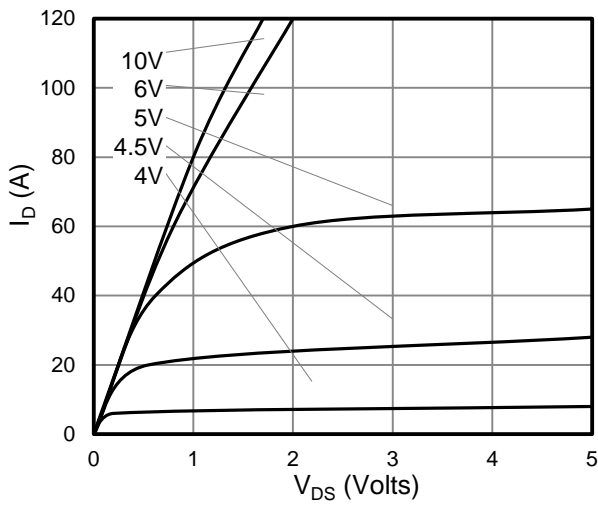


Figure 1: On-Region Characteristics

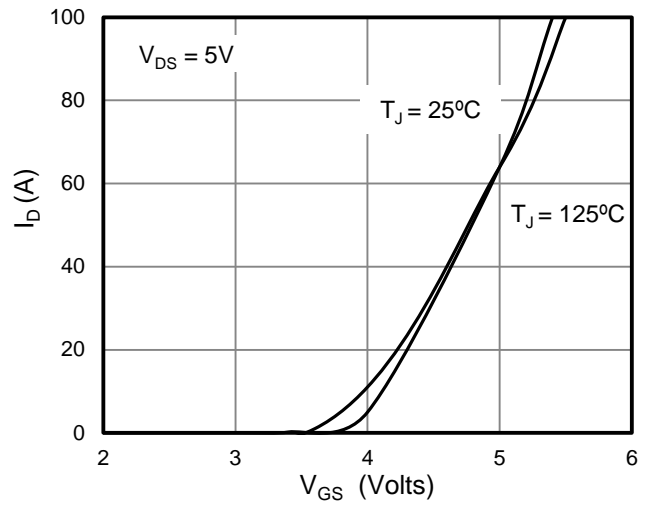


Figure 2: Transfer Characteristics

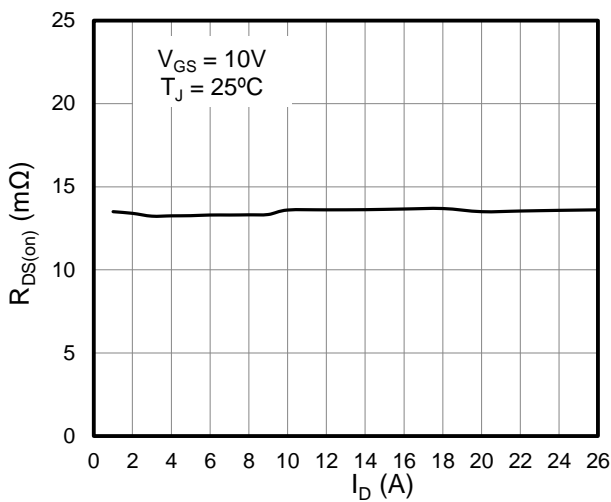


Figure 3: On-Resistance vs. Drain Current

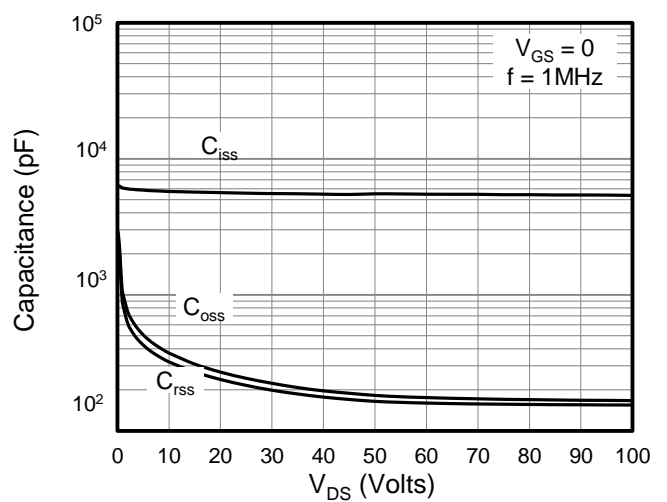


Figure 4: Capacitance Characteristics

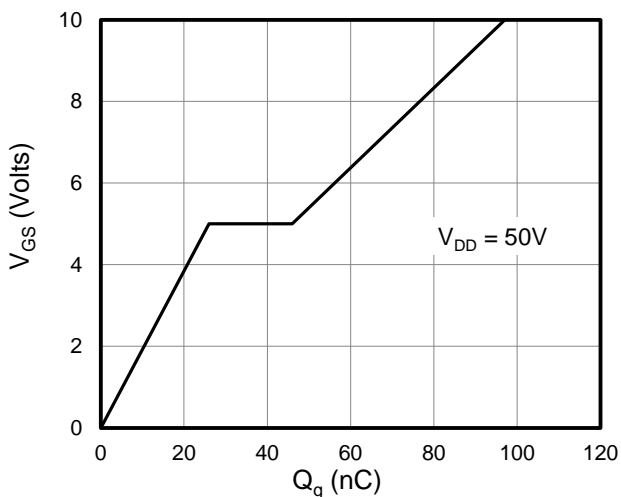


Figure 5: Gate Charge Characteristics

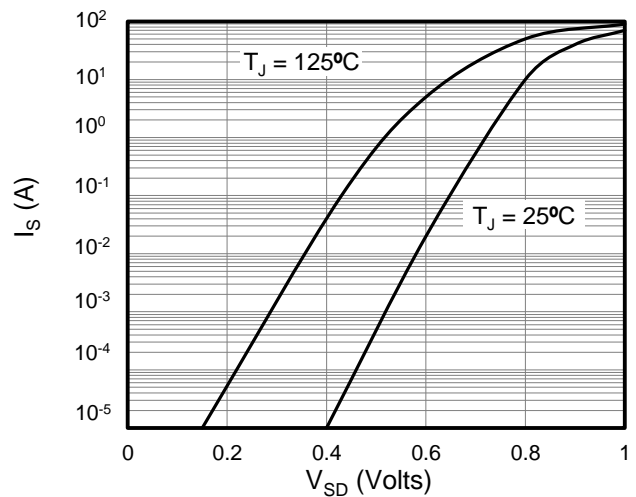


Figure 6: Body Diode Forward Voltage



Typical Characteristics  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

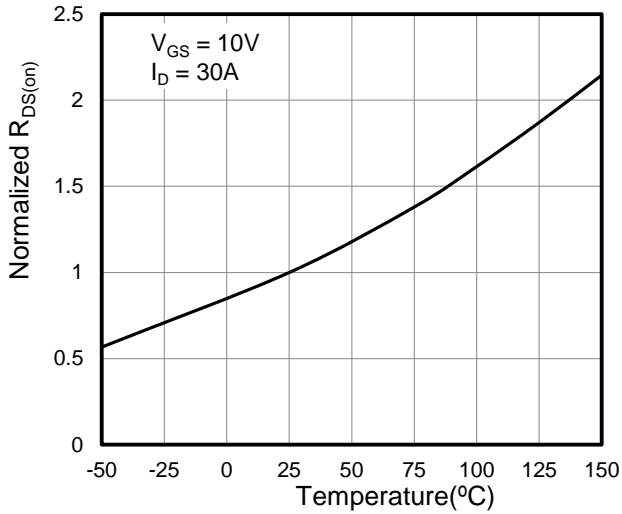


Figure 7: On-Resistance vs. Junction Temperature

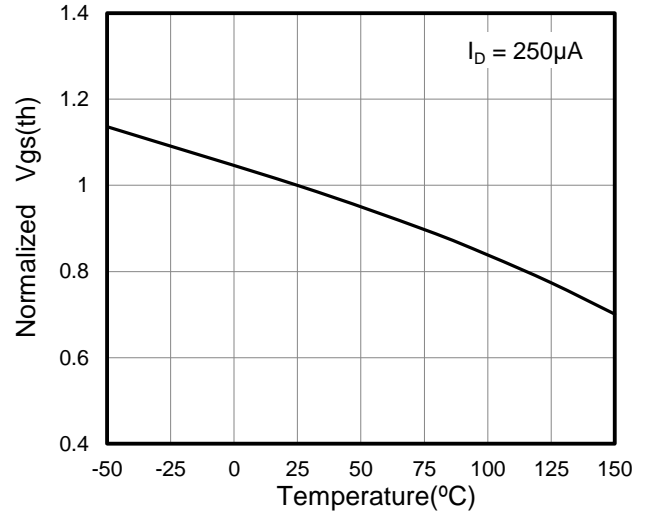


Figure 8:  $V_{gs(th)}$  vs. Junction Temperature

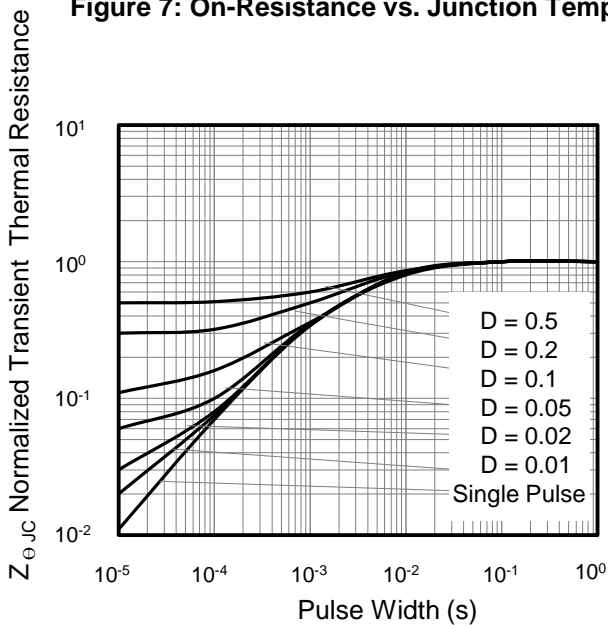


Figure 9: Normalized Transient Thermal Resistance

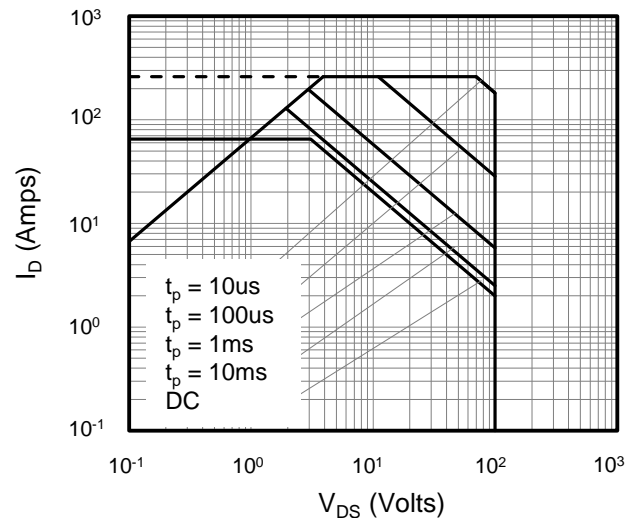


Figure 10: Safe Operating Area



Figure A: Gate Charge Test Circuit and Waveform

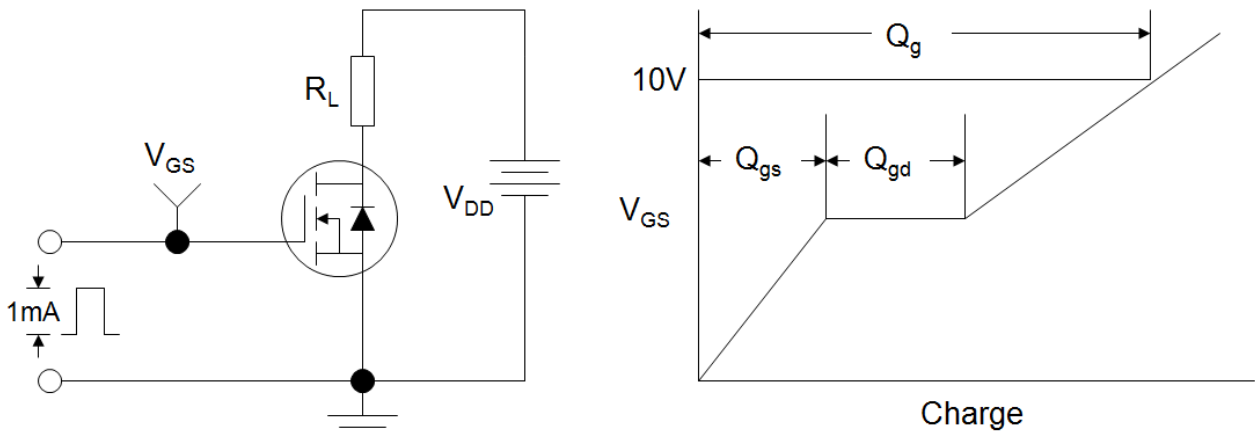


Figure B: Resistive Switching Test Circuit and Waveform

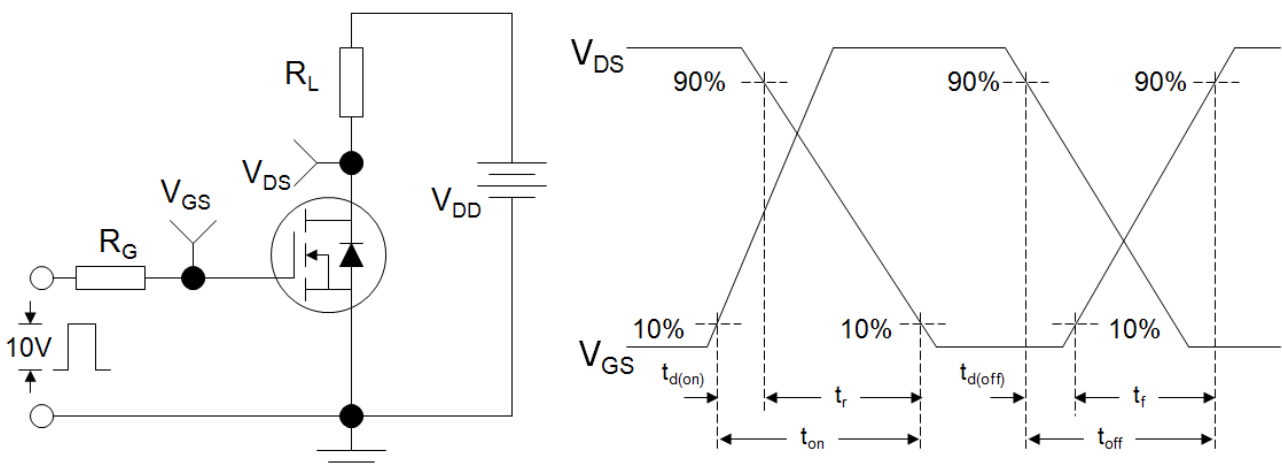
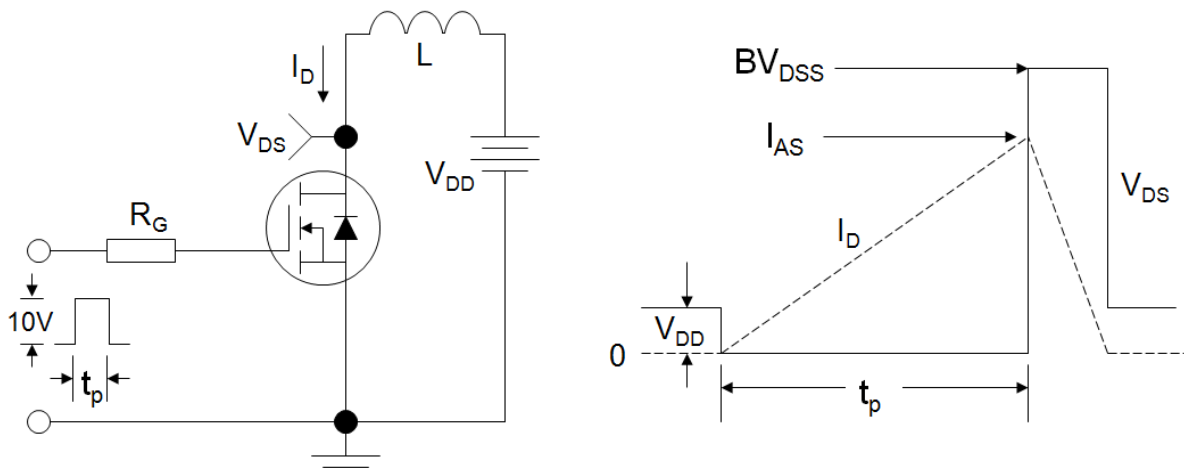
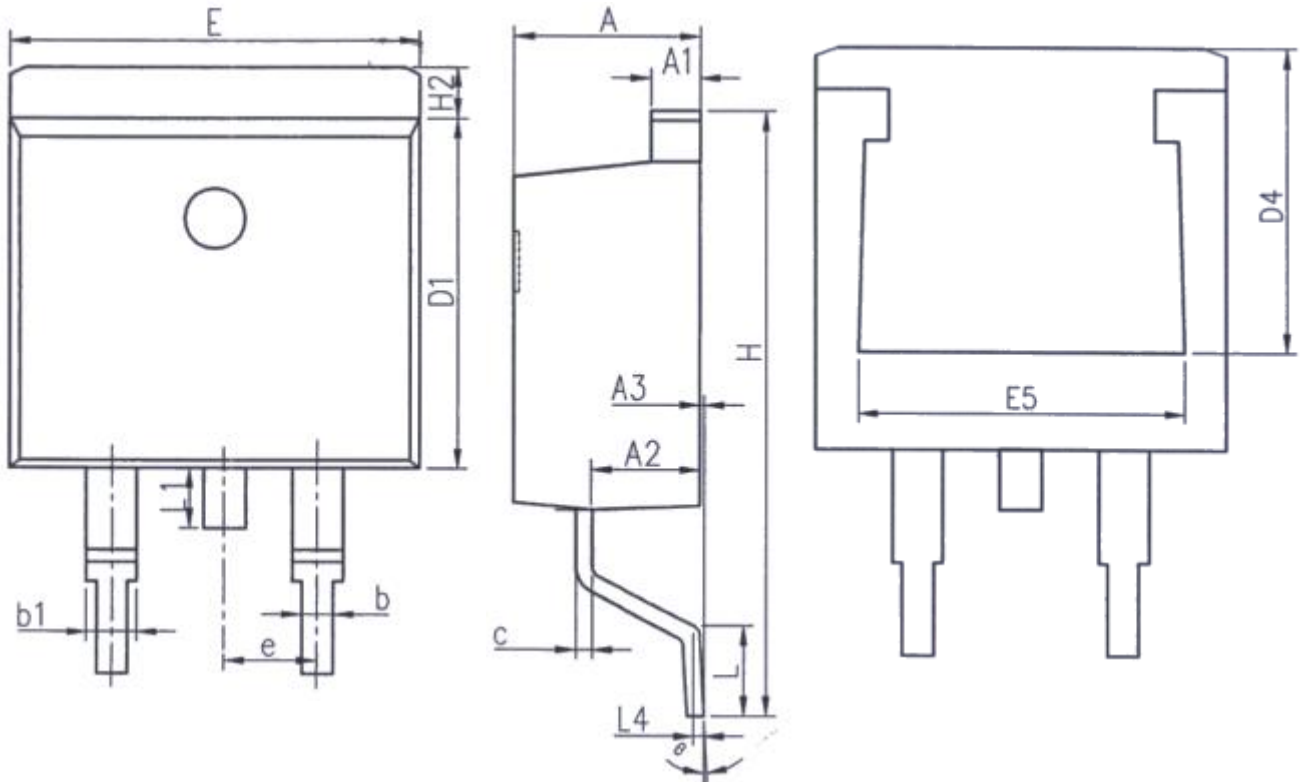


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





### TO-263(华天)

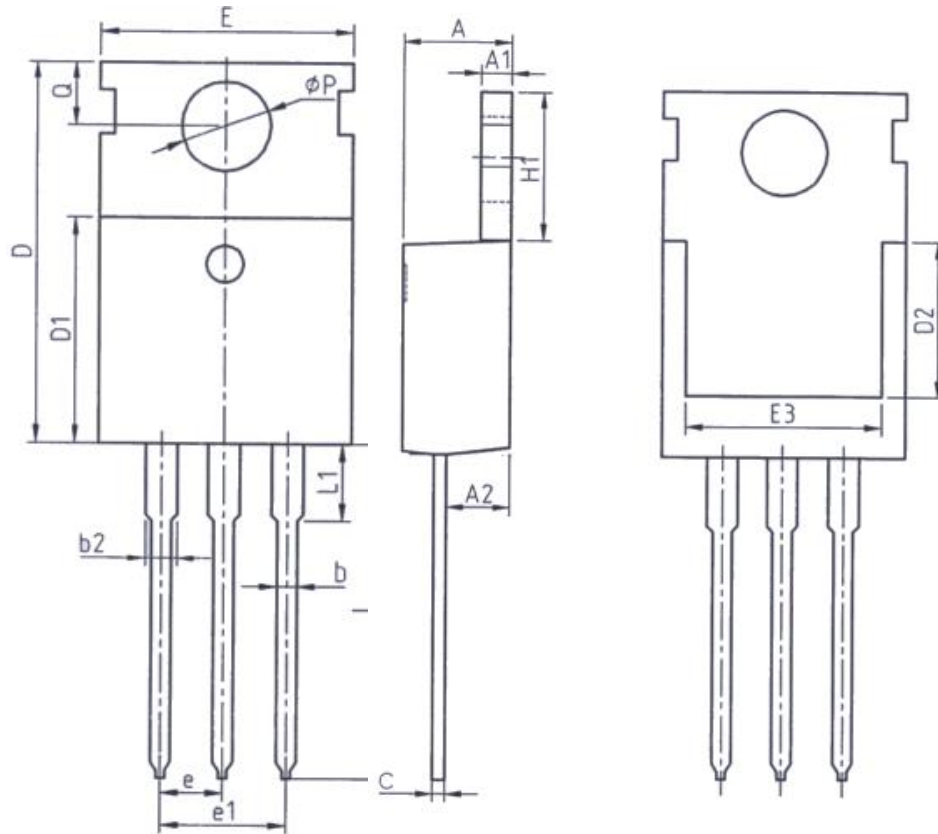


Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.22	1.42
A2	2.49	2.89
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.30	0.53
D1	8.50	8.90
D4	6.60	-

Unit: mm		
Symbol	Min.	Max.
E	9.86	10.36
E5	7.06	-
e	2.54BSC	
H	14.70	15.50
H2	1.07	1.47
L	2.00	2.60
L1	1.40	1.70
L4	0.25BSC	
θ	0°	9°



## TO-220(华天)

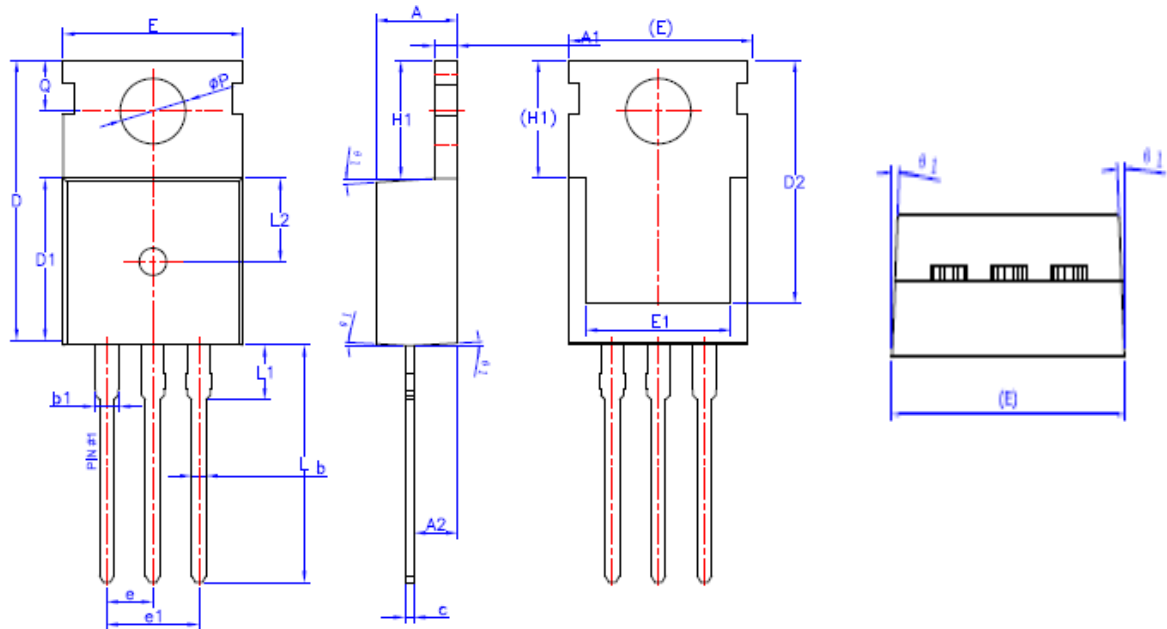


Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	-
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
P	3.40	3.80
Q	2.60	3.00



### TO-220(集佳)



SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	—	0.90
b1	1.27	—	1.40
c	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	—	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54BSC		
e1	5.08BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	—	—	3.50
L2	4.60REF		
$\phi P$	3.55	3.60	3.65
Q	2.73	—	2.87
$\theta 1$	1°	3°	5°





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